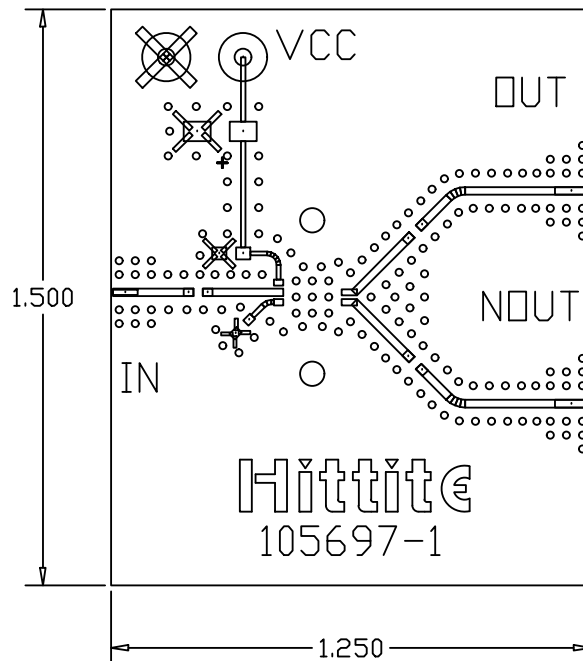


D
C
B
A

5 4 3 2 1
DO NOT SCALE PRINT



REVISION				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	2/20/02	EW

MET-1	1/2 OZ COPPER	0.010"±0.001 ROGERS 4350 SEE NOTE# 1	↑
MET-2	1/2 OZ COPPER	.016" 4403 (2 LAYERS)	0.062
MET-3	1/2 OZ COPPER	0.030"±0.002 ROGERS 4350 SEE NOTE# 1	↓
MET-4	1/2 OZ COPPER		0.067

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350, HALF OUNCE COPPER BOTH SIDES.
2. FINISH: GOLD PLATE PER MIL-G-45204, TYPE III, GRADE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 50 TO 100 MICROINCHES.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ±.003" OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ±.003" MAX
7. BOARD WARPAGE: .010" PER LINEAR INCH MAX
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK
9. TOLERANCE ON PCB ROUTE IS ±.005"
10. PLATING THICKNESS .0018"±.0005 FOR MET-1 AND MET-2
11. APPLY LPI SOLDERMASK TOPSIDE ONLY. COLOR: GREEN
*** SOLDERMASK TO BE APPLIED AS DESIGNED. ANY ADJUSTMENTS TO SOLDERMASK MUST FIRST BE APPROVED BY HITTITE MICROWAVE.
*** SOLDERMASK GERBER FILE IS NEGATIVE IMAGE
12. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPERATION.
13. METAL ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.

CRITICAL LINE WIDTH = .020 ± .001 ADJUST PROCESS TO ACHIEVE WIDTH

TABLE 1 : HOLE DIAMETERS

LETTER DESIG.	DIAMETER	QTY	TYPE	NOTES
NONE	0.018	153	PTH	+0.000/-0.008
NONE	0.043	2	PTH	+0.003/-0.003
NONE	0.064	2	PTH	+0.002/-0.002

UNLESS OTHERWISE SPECIFIED:	
DIMENSIONS ARE IN INCHES (MM)	
DRAWING PRACTICES PER MIL-STD-100	
TOLERANCES:	
.XX	+/- .01
.XXX	+/- .005
ANGLES	+/- .5 DEG

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

DRAWN	E. WATSON 2/20/02
CHECKED	
ENG. APPD.	
HMC APPD.	
RELEASED	



HITTITE MICROWAVE CORPORATIO
12 Elizabeth Drive
Chelmsford, MA 01824

TITLE
EVALUATION PCB
HMC437/438MS8G

SIZE	CODE ID NO.	DRAWING NO.	RI
A	1CN88	105697	
SCALE 2 TO 1	WT	SHEET 1 OF	